

**PATENT ASSIGNMENT**

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
Hsin-Hua Ho	06/15/2007
Wen-Jeng Hwang	06/15/2007
<b>RECEIVING PARTY DATA</b>	
<b>Name:</b>	Lighthouse Technology Co., LTD
<b>Street Address:</b>	No. 7, Datong Rd., Hsin-Chu Industrial Park, Hu-Kuo
<b>City:</b>	Hsin-Chu Hsien
<b>State/Country:</b>	TAIWAN
<b>PROPERTY NUMBERS Total: 1</b>	
<b>Property Type</b>	<b>Number</b>
Application Number:	11782639
<b>CORRESPONDENCE DATA</b>	
Fax Number:	(703)997-4517
<i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i>	
Phone:	3027291562
Email:	Patent.admin.uspto.cr@naipo.com
Correspondent Name:	WINSTON HSU
Address Line 1:	P.O.BOX 506
Address Line 4:	Merrifield, VIRGINIA 22116
ATTORNEY DOCKET NUMBER:	LHTP0016USA
NAME OF SUBMITTER:	WINSTON HSU
Total Attachments: 2 source=LHTP0016USA0_A1_1_NP005#page1.tif source=LHTP0016USA0_A1_1_NP005#page2.tif	

CH \$40.00 11782639

**ASSIGNMENT OF INVENTION**

In consideration of the payment by ASSIGNEE to ASSIGNOR of the sum of One Dollar (\$1.00), the receipt of which is hereby acknowledged, and for other good and valuable consideration.

**ASSIGNOR(S) (Inventors):**

Name: Hsin-Hua Ho Nationality: R.O.C.

Name: Wen-Jeng Hwang Nationality: R.O.C.

Hereby sells, assigns and transfers to

**ASSIGNEE(S):**

Name: Lighthouse Technology Co., LTD

Address: No. 7, Datong Rd., Hsin-Chu Industrial Park, Hu-Kuo, Hsin-Chu Hsien 303, Taiwan, R.O.C.

and the successors and assignees of the ASSIGNEE the entire right, title, and interest in and to any and all improvements which are disclosed in the invention entitled:

"Surface mount type light-emitting diode package device and light-emitting element package device"

Which is found in :

- (a) + U.S. patent application executed on even date
- (b) \_\_\_\_\_ U.S. patent application executed on \_\_\_\_\_
- (c) \_\_\_\_\_ U.S. application serial no. \_\_\_\_\_
- (d) \_\_\_\_\_ patent no. \_\_\_\_\_ issued \_\_\_\_\_

and, in and to, all Letters Patent to be obtained for said invention by the above application or any continuations, continuation-in-part, divisions, renewals, substitutes, or extensions thereof, and as to Letters Patent any reissue or re-examination thereof

ASSIGNOR hereby covenants that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment;

ASSIGNOR further covenants that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said invention and said Letters Patent and legal equivalents as may be known and accessible to ASSIGNOR and will testify as to the same in any interference, litigation or proceeding related thereto and will promptly execute and deliver to ASSIGNEE or its legal representatives any and all papers, instruments or affidavits required to apply for, obtain, maintain, issue and enforce said application, said invention and said Letters Patent and said equivalents thereof which may be necessary or desirable to carry out the proposes thereof.

IN WITNESS WHEREOF, We have hereunto set hand and seal this \_\_\_\_\_ (Date of signing). (請發明人務必簽署上列日期。)

(Type name of inventor)

Signature of INVENTOR

Hsin-Hua Ho

Hsin - Hua Ho 2007-6-15

Wen-Jeng Hwang

Wen-Jeng Hwang 2007-6-15